

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Lopatin, *et al.*

Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

AMENDMENT AND REPLY UNDER 37 CFR 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Examiner Nadav:

This communication is responsive to the Non-Final Office Action dated April 23, 2007,
concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of
this document.

Remarks/Arguments begin on page 6 of this document.

Please amend the application as follows: